

56th Call for Papers

First Call For Papers

56th Electronic Components and Technology Conference

www.ectc.net

To be held in San Diego, California, USA, May 30-June 2, 2006

The Electronic Components and Technology Conference is the premier international electronics symposium that brings together the best in packaging, components and microelectronic systems science, technology and education in an environment of cooperation and technical exchange. The ECTC is jointly sponsored by the Components, Packaging and Manufacturing Technology Society of the IEEE and the Electronic Components, Assemblies and Materials Association of the EIA. You are invited to submit abstracts that provide non-commercial information on new developments, technology and knowledge in the following areas:

Advanced Packaging:

New packaging technologies, systems packaging, designs, materials and configurations addressing performance density and cooling for single chip, multi-chip, wafer-level, MEMS and power packages. Special emphasis on flip-chip, fine pitch and high lead count packaging in CSP, BGA, CGA, LGA, and SMT packages.

Components & RF:

New passive or active component technologies, integrated -embedded components, RF and wireless component applications, component performance, and systems and reliability.

Education:

Education for engineering curricula in the 21st century and collaborative research and engineering programs between universities, government, or industry; development and the use of multimedia for packaging education.

Interconnections:

First-level electronic interconnection technologies including: flip-chip, 3D interconnect, lead-free interconnect, MEMS interconnect, under bump metallurgy, substrate metallurgy and interconnect wire-bonding, TAB, conductive polymers for interconnect, wafer- and device-level interconnection, electrical issues of advanced interconnect structures and novel interconnects, electromigration of bumped interconnects.

Manufacturing Technology:

Processes and equipment for wafer thinning, bumping and stacking, chip packaging, high-density and embedded component substrates, test and burn-in. Emphasis on cost, yield, performance and environmental improvements, process characterization, new product introduction and ramp, design for flexible manufacturing and testing.

Materials & Processing:

Technology, development and application of adhesives, encapsulants, flip-chip underfills, solders and alloys, magnetic and optical materials, ceramics, composites, dielectrics, thin films, thermal materials, bonding and plating processes.

Modeling & Simulation:

Electrical, thermal, optical, mechanical modeling, simulation, characterization and packaging solutions, including system-level applications.

Special Topic: see website for details

A special topic addressing new emerging technologies and applications is selected for ECTC. Please see the website www.ectc.net for details.

Optoelectronics:

Packaging for fiber-optic modules, infra-red wireless, consumer optoelectronics, flat-panel, projection and microdisplays, solid-state lighting, optical amplifiers, lasers, detectors, OEICs, optical data interconnect, optical backplanes, passive components, and WDMs.

Posters:

Papers may be submitted on any of the listed major topics; presentation of papers in a poster format is highly encouraged at ECTC.

Quality & Reliability:

Assessment, failure analysis, reliability testing and data analysis, failure and acceleration models, qualification of components and systems, KGD, incremental quality improvement, and TQM.

At the discretion of the program committee, submitted abstracts may be considered for poster presentation.

You are invited to submit a 750-word abstract that describes the scope, content, and key points of your proposed paper via the website at www.ectc.net. If you have any questions, contact

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Abstracts must be received by 15 October, 2005.

All abstracts must be submitted electronically at www.ectc.net. You must include the mailing address, business telephone number, FAX number and email address of presenting author(s) and affiliations of all authors with your submission.

Professional Development Courses

In addition to abstracts for papers, proposals are solicited from individuals interested in teaching educational professional development courses (4 hours) on topics described in the Call for Papers. Using the format "Course Objectives/Course Outline/Who Should Attend," 200 word proposals must be submitted via the website at www.ectc.net by **October 15, 2005**. If you have any questions, contact:

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